

ABSTRACT

A wiring board comprising: a wiring laminate portion including dielectric layers containing polymeric material and conductor layers laminated alternately so as to form a first main surface out of one of said dielectric layers; and a plurality of metal terminal pads disposed on said first main surface; wherein: each of said metal terminal pads has a structure in which a Cu-plated layer is disposed on a side of said first main surface and an Au-plated layer is disposed in an outermost surface layer portion of said metal terminal pad, while an electroless Ni-plated layer having a P content not higher than 3% by weight is disposed as a barrier metal layer between said Cu-plated layer and said Au-plated layer.

15